

U.S. Application No. 10/502,117
Reply to Office Action of August 23, 2006
Amendment dated: January 23, 2007

AMENDMENTS TO THE CLAIMS:

This listing of claims shall replace all prior versions, and listings, of claims in the application:

1. (Previously Presented) A high-frequency module including a wiring pattern formed in an organic insulative layer and a plurality of conductive parts forming passive elements and distributed parameter elements, which transmit a high-frequency signal,
each of the conductive parts being formed correspondingly to an area of the organic insulative layer where no woven glass fabric is laid, and
wherein the organic insulative layer is formed from among liquid crystal polymer, benzocyclobutene, polyimide, polynorbornene, polyphenylether, polytetrafluoroethylene, bismaleimide-triazine, which is low in specific inductive capacity and loss, or any one of these organic materials also having a ceramic powder dispersed therein.
2. (Original) The high-frequency module according to claim 1, wherein each of the conductive parts is covered with a ground layer formed on the organic insulative layer to form a strip structure or a micro-strip structure.
3. (Previously Presented) The high-frequency module according to claim 1, wherein the passive elements comprise one or more of an inductor, capacitor, or resistor formed with the thin film technology.
4. (Previously Cancelled)

U.S. Application No. 10/502,117
Reply to Office Action of August 23, 2006
Amendment dated: January 23, 2007

5. (Previously Presented) A high-frequency module comprising:

a base substrate block comprising an organic substrate having formed on a main side thereof a plurality of wiring layers each including an organic insulative layer and a wiring pattern and having at least the uppermost one of the wiring layers flattened to form a buildup surface; and

an elements block having formed in an organic insulative layer formed over a main side of the buildup surface of the base substrate block a wiring pattern and a plurality of conductive parts forming passive elements and distributed parameter elements, which transmit a high-frequency signal,

each of the conductive parts of the elements block is formed correspondingly to an area of the organic insulative layer where no woven glass fabric is laid, and

wherein the organic substrate and organic insulative layer are formed from among liquid crystal polymer, benzocyclobutene, polyimide, polynorbornene, polyphenylether, polytetrafluoroethylene, bismaleimide-triazine, which is low in specific inductive capacity and loss, or any one of these organic materials also having a ceramic powder dispersed therein.

6. (Original) The high-frequency module according to claim 5, wherein the base substrate block has a ground pattern in a portion of the organic insulative layer corresponding to the conductive parts and no woven glass fabric is laid at least between the ground pattern and conductive parts.

U.S. Application No. 10/502,117
Reply to Office Action of August 23, 2006
Amendment dated: January 23, 2007

7. (Original) The high-frequency module according to claim 5, wherein being shielded by a ground pattern formed on the organic insulative layer to enclose the perimeters of the conductive parts, the conductive parts form together a strip structure or a micro-strip structure.

8. (Original) The high-frequency module according to claim 5, wherein the wiring layers in the base substrate block have no woven glass fabric formed in portions thereof opposite to areas where the conductive parts are formed.

9. (Previously Presented) The high-frequency module according to claim 5, wherein the passive elements comprise one or more of an inductor, capacitor, or resistor formed with the thin film technology.

Claim 10. (Cancelled)

11. (Previously Presented) A method of producing a high-frequency module, comprising the steps of forming a base substrate block and an elements block, respectively,

in the base substrate block forming step, there is formed, on a main side of an organic substrate, a plurality of wiring layers each including an organic insulative layer and a predetermined wiring pattern, and a buildup surface is formed by flattening at the uppermost one of the wiring layers; and

U.S. Application No. 10/502,117
Reply to Office Action of August 23, 2006
Amendment dated: January 23, 2007

in the elements block forming step, there is formed, in the organic insulative layer formed on the buildup surface of the base substrate block, a wiring pattern and a plurality of conductive parts forming passive elements and distributed parameter elements, which transmit a high-frequency signal,

each of the conductive parts of the elements block being formed correspondingly to an area of the organic substrate where no woven glass fabric is laid, and

wherein the organic substrate and organic insulative layer are formed from among liquid crystal polymer, benzocyclobutene, polyimide, polynorbornene, polyphenylether, polytetrafluoroethylene, bismaleimide-triazine, which is low in specific inductive capacity and loss, or any one of these organic materials also having a ceramic powder dispersed therein.

12. (Original) The method according to claim 11, wherein the base substrate block forming step, a ground pattern is formed in a portion of the organic insulative layer corresponding to the conductive parts and no woven glass fabric is laid at least between the ground pattern and conductive parts.

13. (Original) The method according to claim 11, wherein:

in the base substrate and element forming layer forming steps, a ground pattern is formed on the organic insulative layer to enclose the perimeters of the conductive parts; and

being shielded by the ground pattern, the conductive parts form together a strip structure or a micro-strip structure.

U.S. Application No. 10/502,117
Reply to Office Action of August 23, 2006
Amendment dated: January 23, 2007

14. (Original) The method according to claim 11, wherein the wiring layers in the base substrate block have no woven glass fabric formed in portions thereof opposite to areas where the conductive parts are formed.

Claim 15. (Cancelled)

16. (Previously Presented) A high-frequency module comprising:

a base substrate block comprising an organic substrate containing a woven glass fiber and having formed on a main surface thereof a plurality of wiring layers each including an organic insulative layer and a wiring pattern but containing no woven glass fiber, and having at least the uppermost one of the wiring layers flattened to form a buildup surface, and wherein an electrical ground layer is formed between the woven glass fiber substrate and the plurality of wiring layers in order to electrically isolate subsequent wirings from the woven glass fiber; and

an elements block having formed in an organic insulative layer formed on the main side of the buildup surface of the base substrate block a wiring pattern and a plurality of conductive parts forming passive elements and distributed parameter elements, which transmit a high-frequency signal,

each of the conductive parts of the elements block is formed correspondingly to an area of the organic insulative layer where no woven glass fabric is laid above the ground layer formed in the base substrate block.

U.S. Application No. 10/502,117
Reply to Office Action of August 23, 2006
Amendment dated: January 23, 2007

17. (Previously Presented) A high-frequency module comprising:

upper and lower organic substrates containing woven glass fiber attached together with one or more wiring layers therebetween, each wiring layer including an organic insulative layer and a wiring pattern but containing no woven glass fiber, and wherein an electrical ground layer is formed between each of the upper and lower substrates and the one or more wiring layers in order to electrically isolate the wiring layers from the woven glass fiber contained in the upper and lower organic substrates, respectively; and

wherein said one or more wiring layers contains at least one element selected from a resonator, filter, or coupler, and

wherein the at least one element is formed corresponding to an area of the wiring layers where no woven glass fabric is laid below the ground layer electrically isolating the upper organic substrate and where no woven glass fabric is laid above the ground layer electrically isolating the lower organic substrate.

18. (Previously Presented) The high-frequency module according to claim 5, wherein said organic substrate includes woven glass fabric, and a ground layer is formed over said organic substrate at least at portions corresponding to positions of said conductive parts in order to electrically isolate said conductive parts from said woven glass fabric, and said plurality of wiring layers contain no woven glass fabric.

19. (Previously Presented) A method of producing a high-frequency module according to claim 11,

U.S. Application No. 10/502,117
Reply to Office Action of August 23, 2006
Amendment dated: January 23, 2007

wherein said organic substrate includes woven glass fabric, and said plurality of wiring layers contain no woven glass fabric, and
said base substrate block forming step includes a step of forming a ground layer over said organic substrate at least at portions corresponding to positions of said conductive parts in order to electrically isolate said conductive parts from said woven glass fabric.

Please add the following new claims:

20. (New) The high-frequency module according to claim 1 wherein the passive elements include at least one inductor or capacitor, and wherein the inductor or capacitor is formed opposite a pattern opening formed between substrate layers.